

### **Customer Information Notification**

Issue Date:17-Apr-2020Effective Date:18-Apr-2020

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MPC5775E/MPC5775B Data

Sheet Updates To Rev.2

# 2020030331

## QUALITY

	Change Category					
	[] Wafer Fab Process	[] Assembly	[] Product Marking	[] Test	[] Design	
		Process		Location		
	[] Wafer Fab Materials	[] Assembly	[] Mechanical Specification	ו[ ]Test	[] Errata	
		Materials		Process		
	] Wafer Fab Location	[] Assembly	[]	[]Test	[] Electrical	
		Location	Packing/Shipping/Labeling	Equipment	spec./Test	
			5 11 5 5		coverage	
I	[] Firmware	[X] Other - Datasheet update for clarification				

#### Description

NXP Semiconductors announces data sheet update for the MPC5775E/MPC5775B from revision 1 to revision 2. The revision history included in the updated document provides a details description of the changes.

Data sheet changes:

1. Page 79: In Figure 42, added optional feature field S.

2. Page 23: In Table 16, updated the footnote (no.13) from "TUE does not apply to differential conversions" to "TUE, Gain, and Offset specifications do not apply to differential conversions".

3. Page 11: In Table 4, added Max value 120uA for 40°C and 360uA for 85°C for ISTBY.

4. Page 30: In Table 17, changed the condition of dGROUP from "Within pass band: Tclk is fADCD\_M / 2" to "Within pass band: Tclk is 2/fADCD\_M".

5. Page 31: Updated the footnote (no.15) of tLATENCY, changed the Register Latency formula from "where fADCD\_S is the after-decimation ADC output data rate, fADCD\_M is the modulator sampling rate and fFM\_PER\_CLK is the frequency of the peripheral bridge clock feeds to the ADC S/D module. REGISTER LATENCY = tLATENCY + 0.5/fADCD\_S + 2 ( $\sim$ +1)/fADCD\_M + 2( $\sim$ +1)/fFM\_PER\_CLK" to "where fADCD\_S is the after-decimation ADC output data rate, fADCD\_M/2 is the modulator sampling rate and fFM\_PER\_CLK" to "where fADCD\_S + 2 ( $\sim$ +1)/fADCD\_M + 2( $\sim$ +1)/fFM\_PER\_CLK" to "where fADCD\_S is the after-decimation ADC output data rate, fADCD\_M/2 is the modulator sampling rate and fFM\_PER\_CLK is the frequency of the peripheral bridge clock feeds to the ADC S/D module. REGISTER LATENCY = tLATENCY = tLATENCY + 0.5/fADCD\_S + 2 ( $\sim$ +1)/fADCD\_M + 2( $\sim$ +1)/fFM\_PER\_CLK".

The MPC5775E/MPC5775B data sheet revision 2 is attached to this notice and can be found at: https://www.nxp.com/products/processors-and-microcontrollers/power-architecture/mpc55xx-5xxx-mcus/ultra-reliablempc57xx-mcus/mpc5775b-and-mpc5775e-microcontrollers-for-battery-management-systems-bms-and-inverterapplications:MPC5775B-E?tab=Documentation Tab

Corresponding ZVEI Delta Qualification Matrix ID: SEM-DS-02. Reason

The data sheet has been updated to provide additional technical clarification.

#### Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

**Data Sheet Revision** 

A new datasheet will be issued

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